Peizhi Wang

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/7825767/publications.pdf

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16	316	840585 11	940416 16
papers	citations	h-index	g-index

16	16	16	134
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Prediction of sawing force for single-crystal silicon carbide with fixed abrasive diamond wire saw. Materials Science in Semiconductor Processing, 2017, 63, 25-32.	1.9	61
2	Material removal mechanism and crack propagation in single scratch and double scratch tests of single-crystal silicon carbide by abrasives on wire saw. Ceramics International, 2019, 45, 384-393.	2.3	41
3	Stress analysis in scratching of anisotropic single-crystal silicon carbide. International Journal of Mechanical Sciences, 2018, 141, 1-8.	3.6	28
4	Study on Mechanisms of Photon-Induced Material Removal on Silicon at Atomic and Close-to-Atomic Scale. Nanomanufacturing and Metrology, 2021, 4, 216-225.	1.5	26
5	A scratching force model of diamond abrasive particles in wire sawing of single crystal SiC. Materials Science in Semiconductor Processing, 2017, 68, 21-29.	1.9	23
6	Fracture strength of silicon wafers sawn by fixed diamond wire saw. Solar Energy, 2017, 157, 427-433.	2.9	20
7	Coupling stress caused by thermal and slicing force in KDP crystal slicing with fixed abrasive wire saw. International Journal of Advanced Manufacturing Technology, 2018, 96, 4333-4343.	1.5	17
8	Effect of scratching speed on phase transformations in high-speed scratching of monocrystalline silicon. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2020, 772, 138836.	2.6	14
9	Effect of wire speed on subsurface cracks in wire sawing process of single crystal silicon carbide. Engineering Fracture Mechanics, 2017, 184, 273-285.	2.0	13
10	Interaction of lateral cracks in double scratching of single-crystal silicon carbide. Theoretical and Applied Fracture Mechanics, 2019, 104, 102378.	2.1	13
11	Modeling and simulation of phase transformation and crack formation during scribing of mono-crystalline silicon. International Journal of Mechanical Sciences, 2020, 175, 105527.	3.6	13
12	Fabrication of thin resin-bonded diamond wire and its application to ductile-mode wire sawing of mono-crystalline silicon. Materials Science in Semiconductor Processing, 2021, 126, 105665.	1.9	13
13	Prediction of the thickness for silicon wafers sawn by diamond wire saw. Materials Science in Semiconductor Processing, 2017, 71, 133-138.	1.9	11
14	Effect of speed on material removal behavior in scribing of monocrystalline silicon. Precision Engineering, 2020, 66, 315-323.	1.8	10
15	Crack damage control for diamond wire sawing of silicon: The selection of processing parameters. Materials Science in Semiconductor Processing, 2022, 148, 106838.	1.9	8
16	The interaction of periodically distributed parallel cracks in anisotropic materials subjected to concentrated loads. Engineering Fracture Mechanics, 2018, 199, 131-142.	2.0	5